

DZ2705600L

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit
DZ2S056 in SSSMini2 type package

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: DJ

■ Packaging

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)

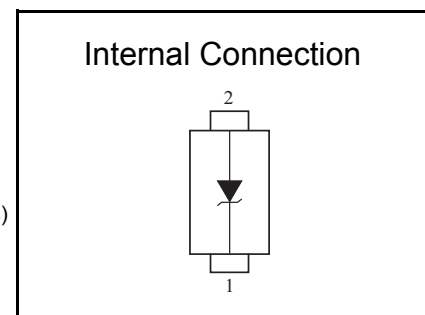
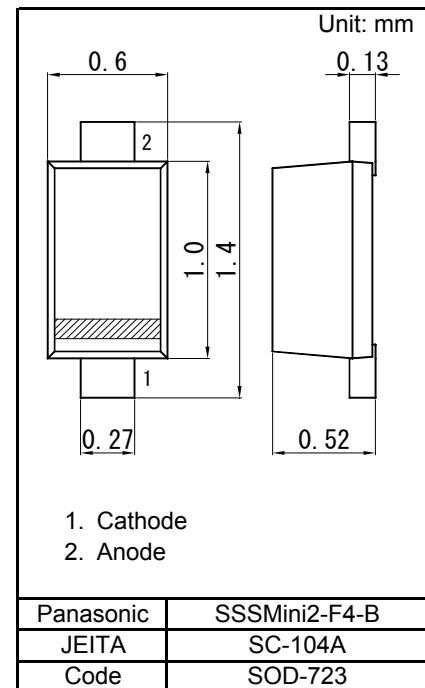
■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation ^{*1}	PT	120	mW
Electrostatic discharge ^{*2}	ESD	±15	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note)*1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)

Solder in (0.4 mm x 0.3 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)



■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	5.32		5.88	V
Zener operating resistance	RZ	IZ = 5 mA			40	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 2.5 V			0.5	μA
Temperature coefficient of zener voltage ^{*3}	SZ	IZ = 5 mA		1.6		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

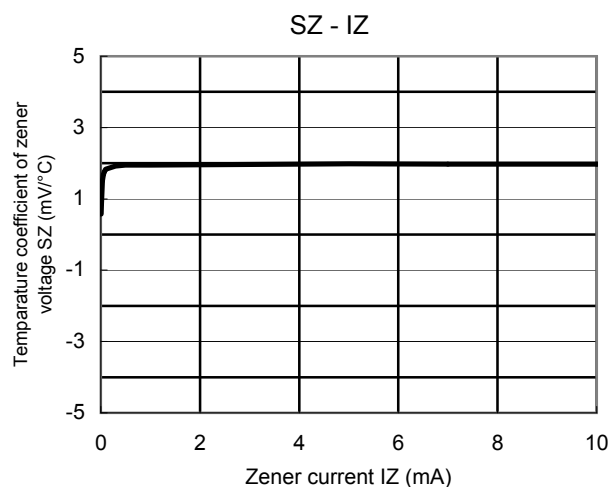
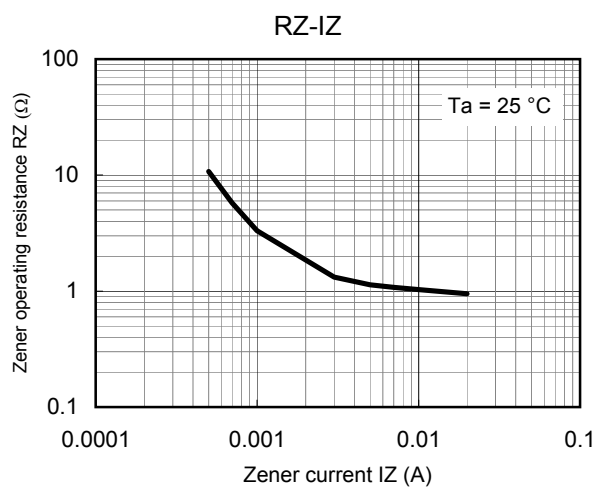
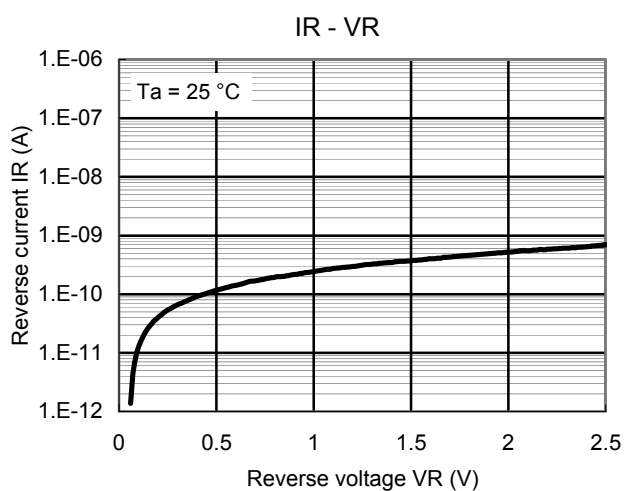
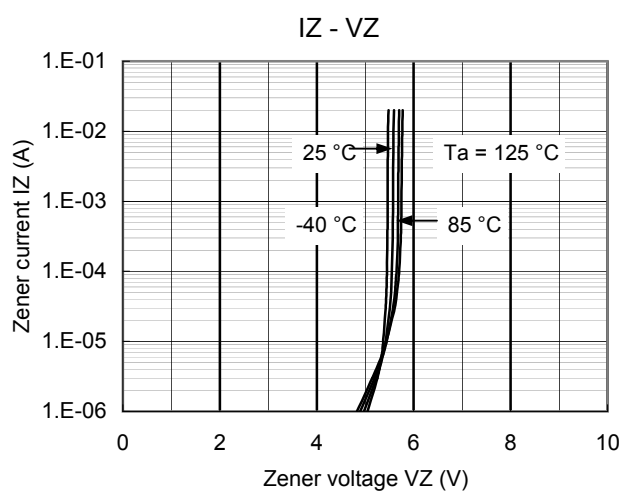
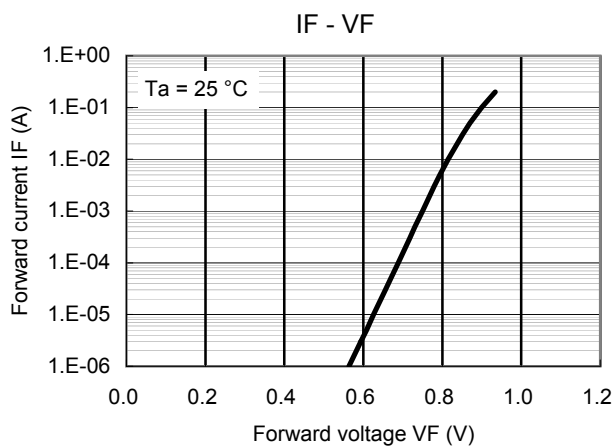
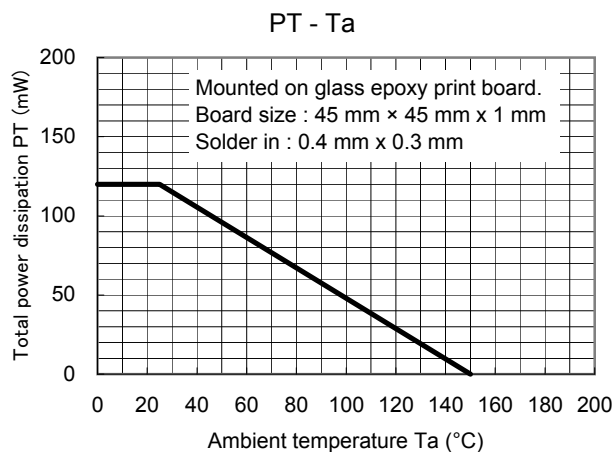
3. *1 The temperature must be controlled 25°C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

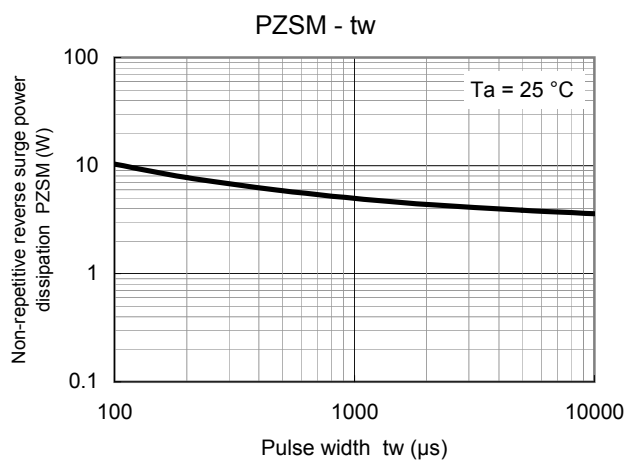
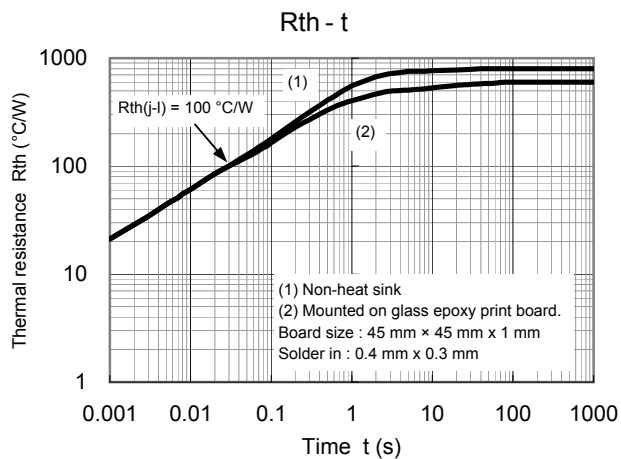
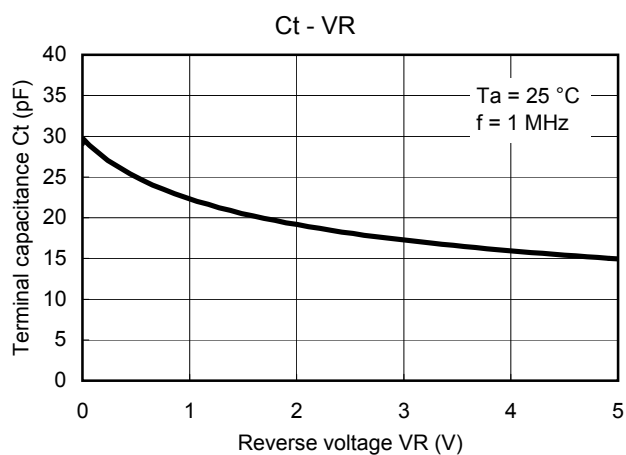
*2 VZ guaranteed 20 ms after current flow.

*3 Tj = 25°C to 150°C

Technical Data (reference)

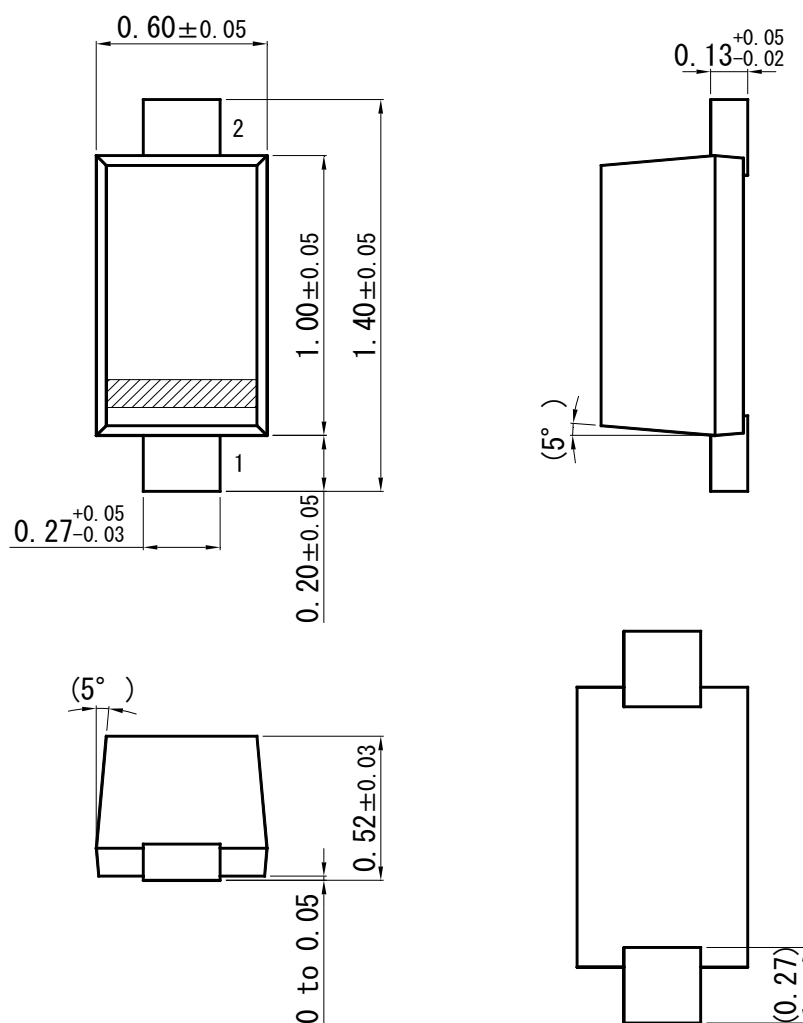


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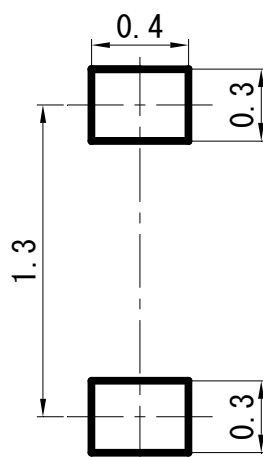


SSSMini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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